Parallel to Serial Conversion

TYPICAL MAXIMUM TYPICAL
TYPE CLOCK FREQUENCY POWER DISSIPATION

′166

35 MHz

360 mW

'LS166A

35 MHz

100 mW

description

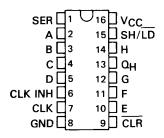
The '166 and 'LS166A 8-bit shift registers are compatible with most other TTL logic families. All '166 and 'LS166A inputs are buffered to lower the drive requirements to one Series 54/74 or Series 54LS/74LS standard load, respectively. Input clamping diodes minimize switching transients and simplify system design.

These parallel-in or serial-in, serial-out shift registers have a complexity of 77 equivalent gates on a monolithic chip. They feature gated clock inputs and an overriding clear input. The parallel-in or serial-in modes are established by the shift/load input. When high, this input enables the serial data input and couples the eight flip-flops for serial shifting with each clock pulse. When low, the parallel (broadside) data inputs are enabled and synchronous loading occurs on the next clock pulse. During parallel loading, serial data flow is inhibited. Clocking is accomplished on the low-to-high-level edge of the clock pulse through a two-input positive NOR gate permitting one input to be used as a clock-enable or clock-inhibit function. Holding either of the clock inputs high inhibits clocking; holding either low enables the other clock input. This, of course, allows the system clock to be free-running and the register can be stopped on command with the other clock input. The clock inhibit input should be changed to the high level only while the clock input is high. A buffered, direct clear input overrides all other inputs, including the clock, and sets all flip-flops to zero.

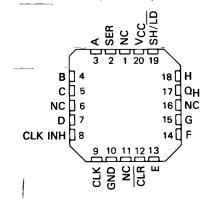
FUNCTION TABLE

		IN	PUTS			INTE	RNAL	ОПТРИТ
CLEAR	SHIFT/	CLOCK	CLOCK	SERIAL	PARALLEL	OUT	PUTS	
CLEAN	LOAD	INHIBIT	CLUCK	SENIAL	AH	Q_A Q_B		σH
L	X	×	Х	Х	×	L	L	L
Н	×	L	L	×	×	QAO	σ_{B0}	QH0
н	L	Ł	1	×	a h	а	b	h
н	н	L	1	н	×	н	\mathtt{q}_{An}	q_{Gn}
н	н	L	t	L	×	L	Q_{An}	a_{Gn}
Н	x	Н	1	×	х	Q _{A0}	a_{B0}	σ _{H0}

SN54166, SN54LS166A . . . J OR W PACKAGE SN74166 . . . N PACKAGE SN74LS166A . . . D OR N PACKAGE (TOP VIEW)

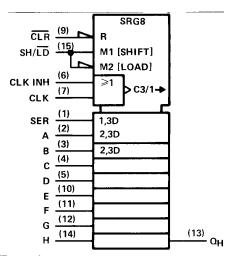


SN54LS166A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol†

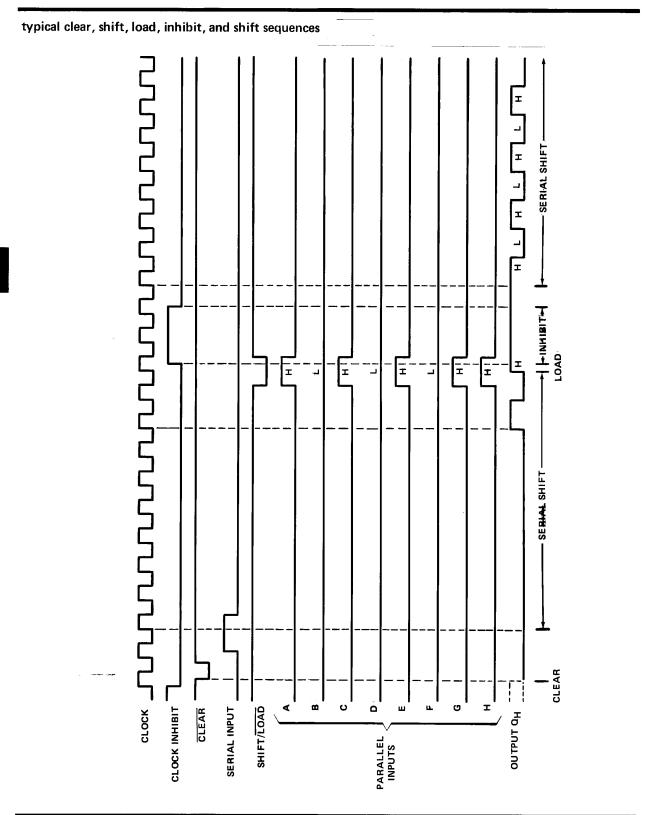


[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

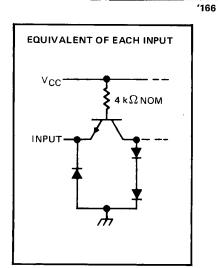
Pin numbers shown are for D, J, N, and W packages.

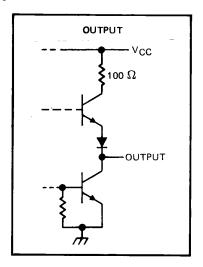
PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



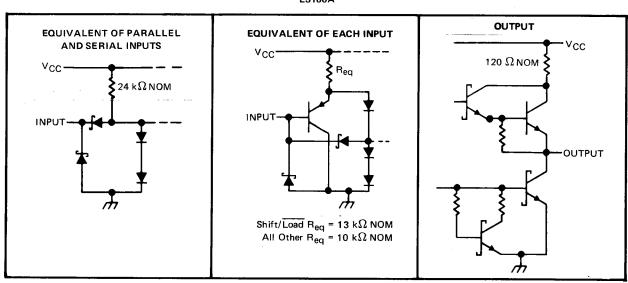


schematics of inputs and outputs



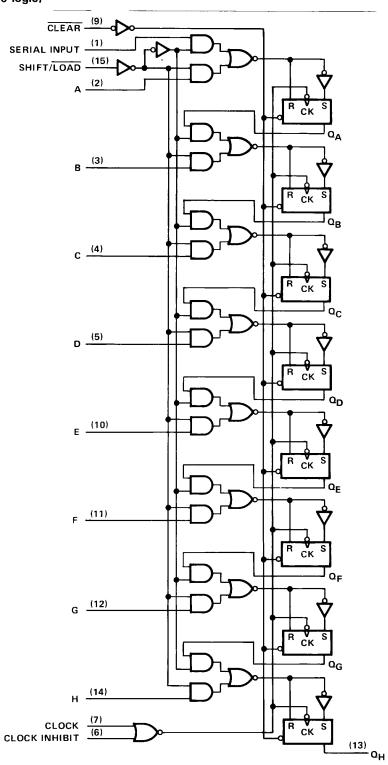


'LS166A



SN54166, SN54LS166A, SN74166, SN74LS166A PARALLEL-LOAD 8-BIT SHIFT REGISTERS

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.



SN54166, SN74166 PARALLEL-LOAD 8-BIT SHIFT REGISTERS

solute maximum ratings over operating free-air temperature range (unless otherwise noted)
Supply voltage, VCC (see Note 1)
Input voltage
Operating free-air temperature range: SN54166 (see Note 2)
SN74166
Storage temperature range
commended operating conditions

	,	SN5416	6		N7416	6	
	MIN	NOM	MAX	MIN	NOM	MAX	TINU
Supply voltage, V _{CC}	4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH			-800			-800	μΑ
Low-level output current, IOL			16			16	mA
Clock frequency, fclock	0		25	0		25	MHz
Width of clock or clear pulse, tw (see Figure 1)	20			20			ns
Mode-control setup time, t _{su}	30			30			ns
Data setup time, t _{SU} (see Figure 1)	20			20			ns
Hold time at any input, th (see Figure 1)	0			0			ns
Operating free-air temperature, TA (see Note 2)	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST CONDITIONS†	5	N5416	6	s	3			
	PARAMETER	TEST CONDITIONS	MIN	MIN TYP‡ MAX		MIN TYP# MAX		MAX	TINU	
v_{iH}	High-level input voltage		2			2			٧	
VIL	Low-level input voltage		1		8.0			0.8	V	
VIĶ	Input clamp voltage	V _{CC} = MIN, I _I = -12 mA			-1.5			-1.5	V	
VOH	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = -800 μA	2,4	3.4		2.4	3.4		v	
VOL	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OL} = 16 mA		0.2	0.4		0.2	0.4	٧	
T ₁	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V			1	1		1	mA	
ЧН	High-level input current	V _{CC} = MAX, V _I = 2.4 V	1		40			40	μА	
ηL	Low-level input current	V _{CC} = MAX, V _I = 0.4 V			-1.6			-1.6	mA	
los	Short-circuit output current§	V _{CC} = MAX	-20		-57	-18		-57	mA	
Icc	Supply current	V _{CC} = MAX, See Note 3		90	127		90	127	mA	

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

- NOTES: 1. Voltage values are with respect to network ground terminal.
 - 2. An SN54166 in the W package operating at free-air temperatures above 113° C requires a heat-sink that provides a thermal resistance from case to free air, $R_{\theta CA}$, of not more than 48° C/W.
 - 3. With all outputs open, 4.5 V applied to the serial input, all other inputs except the clock grounded, I_{CC} is measured after a momentary ground, then 4.5 V, is applied to the clock.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{ C}$

-	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}	Maximum clock frequency		25	35		MHz
	Propagation delay time, high-to-				25	
^t PHL	low-level output from clear	$C_1 = 15 pF$, $R_1 = 400 \Omega$,		23	35	ns
	Propagation delay time, high-to-	C _L = 15 pF, R _L = 400 Ω , See Figure 1		20		
^t PHL	low-level output from clock	See Figure 1		20	30	ns
	Propagation delay time, low-to-			17	20	-
^t PLH	high-level output from clock			17	26	ns



 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

 $[\]S$ Not more than one output should be shorted at a time.

SN54LS166A, SN74LS166A PARALLEL-LOAD 8-BIT SHIFT REGISTERS

absolute maximum ratings over opera		
Supply voltage, VCC (see Note 1)	· · · · · · · · · · · · · · · · · · ·	 7 V
Input voltage		
Operating free-air temperature range:	SN54LS166A	 – 55°C to 125°C
	SN74LS166A	 0°C to 70°C
Storage temperature range		 – 65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SI	N54LS1	66A	SN	174LS1	66A	
		MIN	TYP	MAX	MIN	TYP	MAX	TINU
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
v_{IH}	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
Юн	High-level output current			- 0.4			- 0.4	mA
lor	Low-level output current			4			8	mA
f _{clock}	Clock frequency	0	_	25	0		25	MHz
t _w	Width of clear pulse (See Figure 1)	20			20			ns
t _w	Width of clock pulse (See Figure 1)	25			25			-
t _{su}	Mode-control setup time	30			30			ns
tsu	Data setup time (See Figure 1)	20			20			ns
th	Hold time at any input (See Figure 1 and Note 4)	0		•	0			ns
TA	Operating free air temperature	– 55		125	0		70	°c

NOTE 4: The hold time limit of 0 ns applies only if the rise time is less than or equal to 10 ns.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITION	c†	81	154LS16	66A	SN	UNIT		
TANAMETER	TEST CONDITION		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
V _{IK}	V _{CC} = MIN, I _I = − 18 mA				- 1.5			– 1.5	V
Voн	$V_{CC} = MIN, V_{IH} = 2 V, V_{IOH} = -0.4 \text{ mA}$	L=MAX,	2.5	3.4		2.7	3.4		V
	V _{CC} = MIN, V _{IH} = 2 V, I _O	L = 4 mA		0.25	0.4		0.25	0.4	— ,
VOL	VIL = MAX	L≈8mA					0.35	0.5	†
. Ij	V _{CC} = MAX, V _I = 7 V				0.1			0.1	mA
ЧН .	V _{CC} = MAX, V _I = 2.7 V				20			20	μΑ
IΙL	V _{CC} = MAX, V _I = 0.4 V				- 0.4			- 0.4	mA
los§	V _{CC} = MAX		- 20		– 100	20		- 100	mA
Icc	V _{CC} = MAX, See Note 5			20	32		20	32	mA

 ${\it t} For \ conditions \ shown \ as \ MIN \ or \ MAX, \ use \ the \ appropriate \ value \ specified \ under \ recommended \ operating \ conditions.$

‡All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ}\text{C}$.

§Not more than one output should be shorted at a time, and duration for short-circuit should not exceed one second.

NOTE 5: With all outputs open, 4.5 V applied to the serial input and all other inputs except the clock grounded, ICC is measured after a momentary ground, than 4.5 V, is applied to clock.

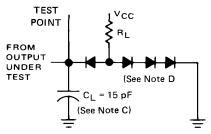
switching characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
fmax	Maximum clock frequency		25	35		MHz
ta	Propagation delay time, high-to-					
tPHL	low-level output from clear	0 45 5 0 010	'	19	30	ns
*=	Propagation delay time, high-to-	$C_L = 15 \text{pF}, R_L = 2 \text{k}\Omega,$		- 4.4		
tPHL	low-level output from clock	See Figure 1	,	14	25	ns
to	Propagation delay time, low-to-					_
tPLH	high-level output from clock		5	11	20	ns



15 4 3

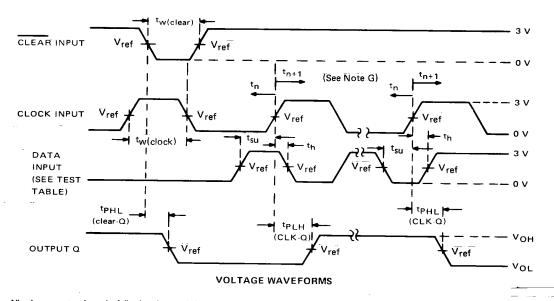
PARAMETER MEASUREMENT INFORMATION



LOAD FOR OUTPUT UNDER TEST

TEST TABLE FOR SYNCHRONOUS INPUTS

DATA INPUT FOR TEST	SHIFT/LOAD	OUTPUT TESTED (SEE NOTE F)
Ŧ	0 V	Q _H at t _{n+1}
Serial Input	4.5 V	Q _H at t _{n+8}



NOTE: A. All pulse generators have the following characteristics: $Z_{OUt} \approx 50Q$; for '166, $t_r \le 7$ ns. and $t_f \le 7$ ns; for 'LS166A, $t_r \le 15$ ns and $t_f \le 6$ ns.

- B. The clock pulse has the following characteristics: t_{W(clock)} ≤ 20 ns and PRR = 1 MHz. The clear pulse has the following characteristics: t_{W(clear)} ≤ 20 ns and t_{hold} = 0 ns. When testing f_{max}, vary the clock PRR.
- C. C_L includes probe and jig capacitance.
- D. All diodes are 1N3064, 1N916, or equivalent.
- E. A clear pulse is applied prior to each test.
- F. Propagation delay times (t_{PLH}) and t_{PHL} are measured at t_{n+1} . Proper shifting of data is verified at t_{n+8} with a functional test.
- G. t_n = bit time before clocking transition
 - t_{n+1} = bit time after one clocking transition
 - t_{n+8} = bit time after eight clocking transitions
- H. For '166 $V_{ref} = 1.5 V$; for 'LS166A $V_{ref} = 1.3 V$.

FIGURE 1



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9558301QEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9558301QE A SNJ54166J	Samples
5962-9558301QFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9558301QF A SNJ54166W	Samples
5962-9558301QFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9558301QF A SNJ54166W	Samples
8001701EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8001701EA SNJ54LS166AJ	Samples
8001701EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8001701EA SNJ54LS166AJ	Samples
8001701FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8001701FA SNJ54LS166AW	Samples
8001701FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8001701FA SNJ54LS166AW	Samples
JM38510/30609B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30609B2A	Samples
JM38510/30609B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30609B2A	Samples
JM38510/30609BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30609BEA	Samples
JM38510/30609BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30609BEA	Samples
M38510/30609B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30609B2A	Samples
M38510/30609B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30609B2A	Samples
M38510/30609BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30609BEA	Samples
M38510/30609BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30609BEA	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Sample
SN54166J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54166J	Samples
SN54166J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54166J	Samples
SN54LS166AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS166AJ	Samples
SN54LS166AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS166AJ	Samples
SN74LS166AD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS166A	Samples
SN74LS166AD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS166A	Samples
SN74LS166ADR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS166A	Samples
SN74LS166ADR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS166A	Samples
SN74LS166AN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS166AN	Samples
SN74LS166AN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS166AN	Samples
SN74LS166ANSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS166A	Samples
SN74LS166ANSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS166A	Samples
SNJ54166J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9558301QE A SNJ54166J	Samples
SNJ54166J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9558301QE A SNJ54166J	Samples
SNJ54166W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9558301QF A SNJ54166W	Samples
SNJ54166W	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9558301QF A SNJ54166W	Samples
SNJ54LS166AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 166AFK	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS166AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 166AFK	Samples
SNJ54LS166AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8001701EA SNJ54LS166AJ	Samples
SNJ54LS166AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8001701EA SNJ54LS166AJ	Samples
SNJ54LS166AW	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8001701FA SNJ54LS166AW	Samples
SNJ54LS166AW	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	8001701FA SNJ54LS166AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN54LS166A, SN74LS166A:

Catalog: SN74LS166A

Military: SN54LS166A

NOTE: Qualified Version Definitions:

Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS166ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS166ANSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS166ADR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LS166ANSR	so	NS	16	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9558301QFA	W	CFP	16	1	506.98	26.16	6220	NA
8001701FA	W	CFP	16	1	506.98	26.16	6220	NA
JM38510/30609B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/30609B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74LS166AD	D	SOIC	16	40	507	8	3940	4.32
SN74LS166AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS166AN	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54166W	W	CFP	16	1	506.98	26.16	6220	NA
SNJ54LS166AFK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54LS166AW	W	CFP	16	1	506.98	26.16	6220	NA



SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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